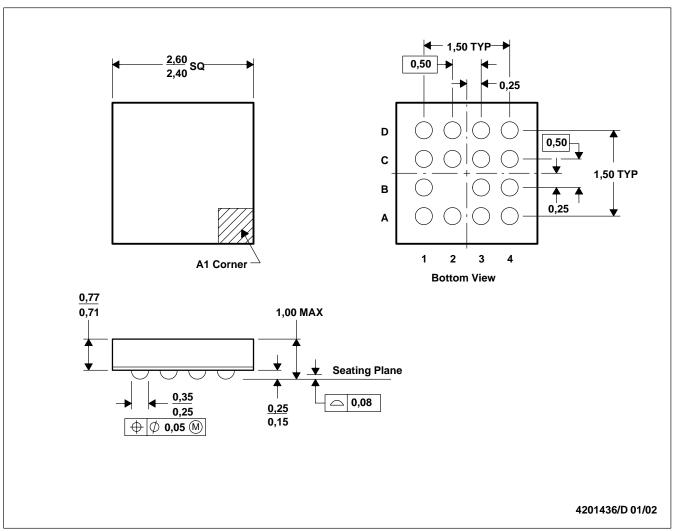
## **MECHANICAL DATA**

MPBG168B - SEPTEMBER 2000 - REVISED FEBRUARY 2002

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

**GQY (S-PBGA-N15)** 

- B. This drawing is subject to change without notice.
- C. MicroStar Junior™ configuration
  D. Falls within JEDEC MO-225

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